

Appl. No. : 10/007,304
Filed : December 5, 2001

50. (Amended) A diffusion barrier for a copper interconnect comprising:
a first layer of metal nitride;
a layer of reactive metal over the first layer of metal nitride; and
a second layer of metal nitride over the layer of reactive metal, wherein the grain boundaries of the first and second metal nitride layers are stuffed with a compound of a metal different from the metal in the nitride layers.

51. (Amended) The diffusion barrier of Claim 50, wherein the compound of a metal different from the metal in the nitride layers is selected from the group consisting of an oxide of the reactive metal and a nitride of the reactive metal.

REMARKS

Prior to examination, Applicants have amended the claims to correct obvious errors and to match follow-on recitations with their antecedents. Applicants submit that the amendments introduce no new matter and are fully supported by the application as filed.

A marked-up version of the amendments is appended on separate pages entitled **VERSION OF AMENDMENTS SHOWING CHANGES MADE**, wherein additions are showing in double-underlining and deletions are shown in ~~strike through~~ text. Also appended for the Examiner's convenience is a clean version of the claims after entry of the amendments.

Respectfully submitted,

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